



/ Revised record

F	2016-3				
G	2019-10-18	1			
H	2019-12-4	2	C _{J1} C _{J2}		
I	2022-6-13	1	±17 V (), ±12 () ±17 kV (), ±12 kV ()		

/ Descriptions

SOT23-6 TVS
Low Capacitance TVS Array in a SOT23-6 Plastic Package.

/ Features

4 ESD I/O 0.35pF

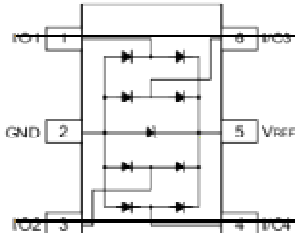
4 ESD protection structures, low capacitance for high-speed interfaces, Capacitance I / O channel is not more than 0.35pF, Low clamping voltage, Low operating voltage, suitable for high speed data transmission lines. HF Product.

/ Applications

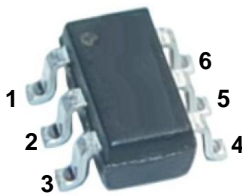
ESD USB 2.0 IEC 61000-4-2(ESD) 17KV (), ±12KV ()

ESD protection for high-speed data lines, such as USB 2.0, set-top boxes, monitors and so on. According to IEC 61000-4-2 (ESD) Standard: ± 17KV (air discharge), ± 12KV (contact discharge).

/ Equivalent Circuit



/ Pinning



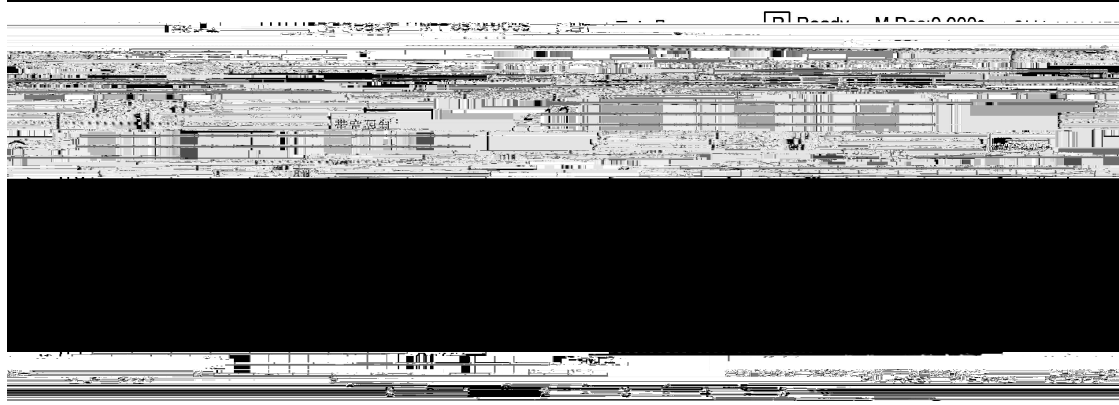
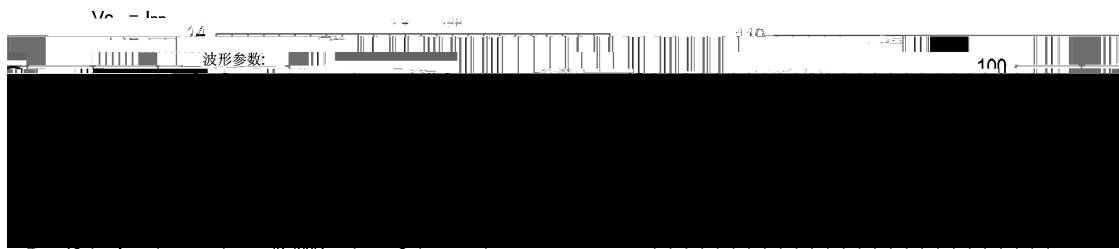
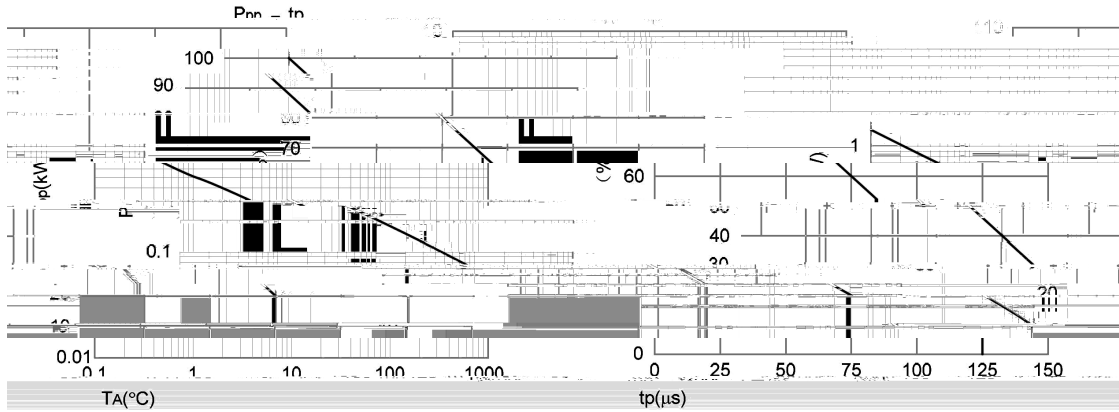
/ Marking

See Marking Instructions.

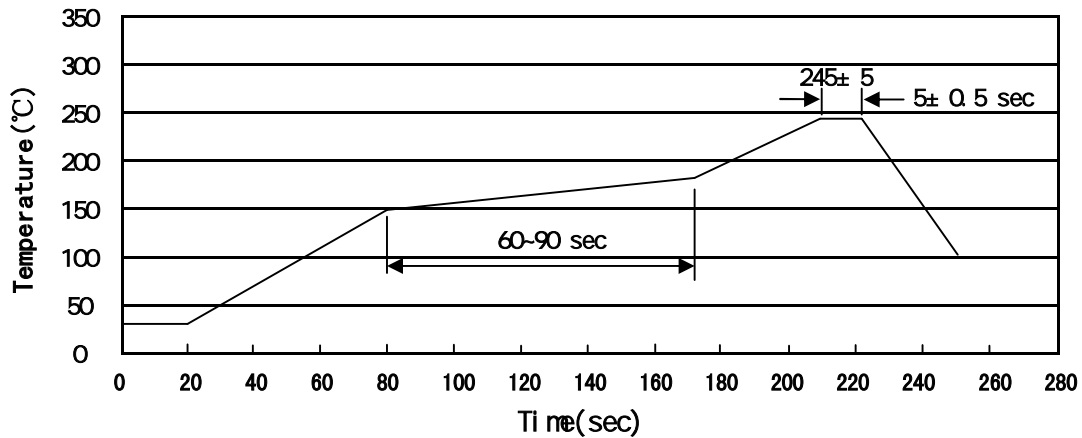
Parameter	Symbol	Rating	Unit
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	150	W



/ Electrical Characteristic Curve



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/盒	Units/Outer Box 只/盒	Reel	Inner Box fl	Outer Box L
SOT23-5/6	3,000	10	30,000	4	120,000	7" x8	210×205×205	445×230×435

/ Notices